

- NOTES - UNLESS OTHERWISE SPECIFIED:
- 1. WORKMANSHIP STANDARDS AND ACCEPTABILITY REQUIREMENTS SHALL MEET IPC-A-610 (LATEST VERSION).
 - 2. THIS DOCUMENT AND RELATED ARTWORK ARE COMPUTER GENERATED. CHANGES ARE TO BE PERFORMED ON THE ORIGINAL DATABASE, 20019325_A-DESIGN.zip
 - 3. ASSEMBLE (SOLDER) AND INSPECT PRINTED WIRING ASSEMBLY PER J-STD-001 (LATEST VERSION), CLASS 2.
 - 4. SOLDER COMPONENTS USING LEADED SOLDER, ITEM 3.
 - 5. CLEAN SOLDER FLUX FROM BOARD SO THAT THERE IS NO DISCERNABLE RESIDUE.
 - 6. FOR SCHEMATIC DIAGRAM SEE JPL DRAWING 20019323.
 - 7. THIS PRINTED WIRING ASSEMBLY CONSISTS OF ONLY SURFACE MOUNT TECHNOLOGY.
 - 8. CROSS-REFERENCE: M1CS-400-10700 ELECTRONIC ID BOARD

REVISION HISTORY					
REV	DESCRIPTION	CAT	DWN	ENGR	SEE JPL DATA MANAGEMENT SYSTEM FOR APPROVAL SIGNATURES AND DATES
A	----- INITIAL RELEASE -----	II	-	-	

TOP ASSEMBLY (Scale =2/1)



(SEE SEPARATE PARTS LIST)

	1	5	U1		5055670281	CONNECTOR, MICRO-LOCK PLUS RIGHT ANGLE		MOLEX
	1	4	J1		DS2401P+	IC, SILICON SERIAL NUMBER 6TSOC		MAXIM-IC
	AR	3			Sn63/Pb37	SOLDER LEADED	J-STD-005A	4
		2						
	1	1			20019324-1	PRINTED WIRING BOARD, ELECTRONIC ID		REV A
	-1	ITEM NO	REFDES	DAI	PART OR IDENTIFYING NO	NOMENCLATURE OR DESCRIPTION	SPECIFICATION	MATERIAL OR NOTE
QTY REQD								

PARTS LIST

CONTRACT NO			
DWN	D. PALMER		
ENGR	D. PALMER		
SEE JPL DATA MANAGEMENT SYSTEM FOR APPROVAL SIGNATURES AND DATES			
TMT			
NEXT ASSEMBLY		USED ON	
APPLICATION			

JET PROPULSION LABORATORY

CALIFORNIA INSTITUTE OF TECHNOLOGY
PASADENA, CA 91109

TITLE

PRINTED WIRING ASSEMBLY,
ELECTRONIC ID

SIZE	DAI	DWG NO	REV
B	23835	20019325	A
SCALE: 2/1		SHEET 1 OF 1	